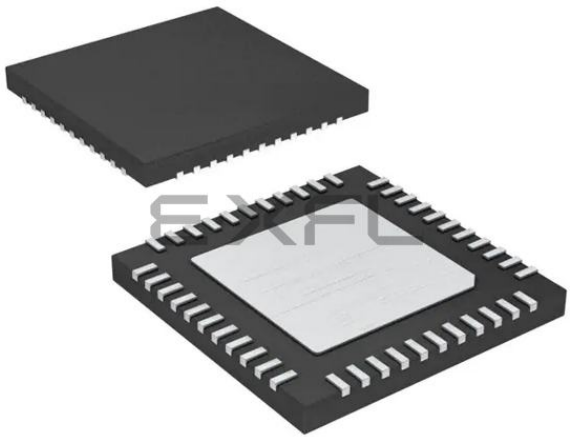

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	10MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	36
Program Memory Size	14KB (8K x 14)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	368 x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 5.5V
Data Converters	A/D 14x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-VQFN Exposed Pad
Supplier Device Package	44-QFN (8x8)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lf777-i-ml

2.2.2.1 Status Register

The Status register contains the arithmetic status of the ALU, the Reset status and the bank select bits for data memory.

The Status register can be the destination for any instruction, as with any other register. If the Status register is the destination for an instruction that affects the Z, DC or C bits, then the write to these three bits is disabled. These bits are set or cleared according to the device logic. Furthermore, the $\overline{TO}$ and $\overline{PD}$ bits are not writable, therefore, the result of an instruction with the Status register as destination may be different than intended.

For example, `CLRF STATUS`, will clear the upper three bits and set the Z bit. This leaves the Status register as `000u u1uu` (where `u` = unchanged).

It is recommended, therefore, that only `BCF`, `BSF`, `SWAPF` and `MOVWF` instructions are used to alter the Status register because these instructions do not affect the Z, C or DC bits from the Status register. For other instructions not affecting any Status bits, see **Section 16.0 "Instruction Set Summary"**.

Note 1:	The C and DC bits operate as a $\overline{\text{borrow}}$ and $\overline{\text{digit borrow}}$ bit, respectively, in subtraction. See the `SUBLW` and `SUBWF` instructions for examples.

REGISTER 2-1: STATUS: ARITHMETIC STATUS REGISTER (ADDRESS 03h, 83h, 103h, 183h)

R/W-0	R/W-0	R/W-0	R-1	R-1	R/W-x	R/W-x	R/W-x
IRP	RP1	RP0	$\overline{TO}$	$\overline{PD}$	Z	DC	C
bit 7							bit 0

bit 7 **IRP:** Register Bank Select bit (used for indirect addressing)
`1` = Bank 2, 3 (100h-1FFh)
`0` = Bank 0, 1 (00h-FFh)

bit 6-5 **RP1:RP0**: Register Bank Select bits (used for direct addressing)
`11` = Bank 3 (180h-1FFh)
`10` = Bank 2 (100h-17Fh)
`01` = Bank 1 (80h-FFh)
`00` = Bank 0 (00h-7Fh)
Each bank is 128 bytes.

bit 4 **$\overline{TO}$**: Time-out bit
`1` = After power-up, `CLRWDT` instruction or `SLEEP` instruction
`0` = A WDT time-out occurred

bit 3 **$\overline{PD}$**: Power-Down bit
`1` = After power-up or by the `CLRWDT` instruction
`0` = By execution of the `SLEEP` instruction

bit 2 **Z**: Zero bit
`1` = The result of an arithmetic or logic operation is zero
`0` = The result of an arithmetic or logic operation is not zero

bit 1 **DC**: Digit Carry/$\overline{\text{borrow}}$ bit (`ADDWF`, `ADDLW`, `SUBLW`, `SUBWF` instructions)
`1` = A carry-out from the 4th low-order bit of the result occurred
`0` = No carry-out from the 4th low-order bit of the result

bit 0 **C:** Carry/$\overline{\text{borrow}}$ bit (`ADDWF`, `ADDLW`, `SUBLW`, `SUBWF` instructions)
`1` = A carry-out from the Most Significant bit of the result occurred
`0` = No carry-out from the Most Significant bit of the result occurred

Note: For $\overline{\text{borrow}}$, the polarity is reversed. A subtraction is executed by adding the two's complement of the second operand. For rotate (`RRF`, `RLF`) instructions, this bit is loaded with either the high or low-order bit of the source register.

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

2.2.2.3 INTCON Register

The INTCON register is a readable and writable register which contains various enable and flag bits for the TMR0 register overflow, RB port change and external RB0/INT pin interrupts.

Note:	Interrupt flag bits are set when an interrupt condition occurs regardless of the state of its corresponding enable bit or the Global Interrupt Enable bit, GIE (INTCON<7>). User software should ensure the appropriate interrupt flag bits are clear prior to enabling an interrupt.

REGISTER 2-3: INTCON: INTERRUPT CONTROL REGISTER (ADDRESS 0Bh, 8Bh, 10Bh, 18Bh)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-x
GIE	PEIE	TMR0IE	INT0IE	RBIE	TMR0IF	INT0IF	RBIF
bit 7							bit 0

bit 7 **GIE:** Global Interrupt Enable bit
1 = Enables all unmasked interrupts
0 = Disables all interrupts

bit 6 **PEIE**: Peripheral Interrupt Enable bit
1 = Enables all unmasked peripheral interrupts
0 = Disables all peripheral interrupts

bit 5 **TMR0IE**: TMR0 Overflow Interrupt Enable bit
1 = Enables the TMR0 interrupt
0 = Disables the TMR0 interrupt

bit 4 **INT0IE**: RB0/INT External Interrupt Enable bit
1 = Enables the RB0/INT external interrupt
0 = Disables the RB0/INT external interrupt

bit 3 **RBIE**: RB Port Change Interrupt Enable bit
1 = Enables the RB port change interrupt
0 = Disables the RB port change interrupt

bit 2 **TMR0IF**: TMR0 Overflow Interrupt Flag bit
1 = TMR0 register has overflowed (must be cleared in software)
0 = TMR0 register did not overflow

bit 1 **INT0IF**: RB0/INT External Interrupt Flag bit
1 = The RB0/INT external interrupt occurred (must be cleared in software)
0 = The RB0/INT external interrupt did not occur

bit 0 **RBIF**: RB Port Change Interrupt Flag bit
A mismatch condition will continue to set flag bit RBIF. Reading PORTB will end the mismatch condition and allow flag bit RBIF to be cleared.
1 = At least one of the RB7:RB4 pins changed state (must be cleared in software)
0 = None of the RB7:RB4 pins have changed state

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

2.5 Indirect Addressing, INDF and FSR Registers

The INDF register is not a physical register. Addressing the INDF register will cause indirect addressing.

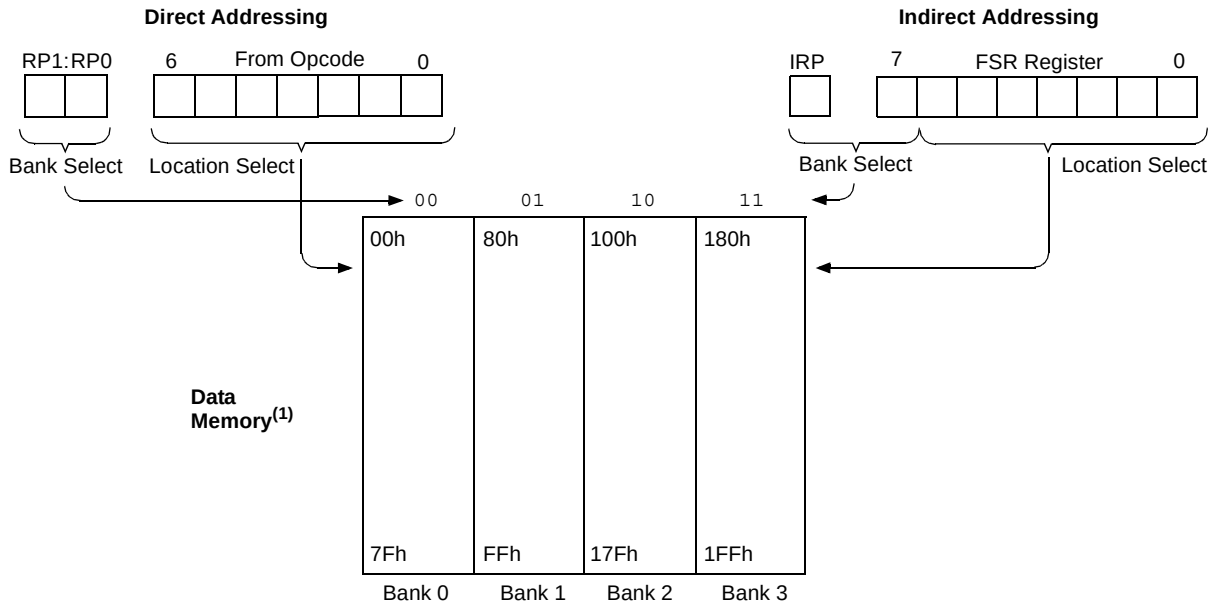
Indirect addressing is possible by using the INDF register. Any instruction using the INDF register actually accesses the register pointed to by the File Select Register, FSR. Reading the INDF register itself indirectly (FSR = 0) will read 00h. Writing to the INDF register indirectly results in a no operation (although Status bits may be affected). An effective 9-bit address is obtained by concatenating the 8-bit FSR register and the IRP bit (Status<7>) as shown in Figure 2-5.

A simple program to clear RAM locations 20h-2Fh using indirect addressing is shown in Example 2-2.

EXAMPLE 2-2: INDIRECT ADDRESSING

```
        MOVLW   0x20    ;initialize pointer
        MOVWF   FSR     ;to RAM
NEXT    CLRF    INDF    ;clear INDF register
        INCF    FSR, F  ;inc pointer
        BTFSS   FSR, 4  ;all done?
        GOTO    NEXT    ;no clear next
CONTINUE
    :                   ;yes continue
```

FIGURE 2-5: DIRECT/INDIRECT ADDRESSING



Note 1: For register file map detail, see Figure 2-2.

4.6.5 CLOCK TRANSITION SEQUENCE

The following are three different sequences for switching the internal RC oscillator frequency:

- Clock before switch: 31.25 kHz (IRCF<2:0> = 000)
  1. IRCF bits are modified to an INTOSC/INTOSC postscaler frequency.
  2. The clock switching circuitry waits for a falling edge of the current clock, at which point CLKO is held low.
  3. The clock switching circuitry then waits for **eight** falling edges of requested clock, after which it switches CLKO to this new clock source.
  4. The IOFS bit is clear to indicate that the clock is unstable and a 4 ms (approx.) delay is started. Time dependent code should wait for IOFS to become set.
  5. Switchover is complete.
- Clock before switch: One of INTOSC/INTOSC postscaler (IRCF<2:0> ≠ 000)
  1. IRCF bits are modified to INTRC (IRCF<2:0> = 000).
  2. The clock switching circuitry waits for a falling edge of the current clock, at which point CLKO is held low.
  3. The clock switching circuitry then waits for **eight** falling edges of requested clock, after which it switches CLKO to this new clock source.
  4. Oscillator switchover is complete.
- Clock before switch: One of INTOSC/INTOSC postscaler (IRCF<2:0> ≠ 000)
  1. IRCF bits are modified to a different INTOSC/ INTOSC postscaler frequency.
  2. The clock switching circuitry waits for a falling edge of the current clock, at which point CLKO is held low.
  3. The clock switching circuitry then waits for **eight** falling edges of requested clock, after which it switches CLKO to this new clock source.
  4. The IOFS bit is set.
  5. Oscillator switchover is complete.

4.6.6 OSCILLATOR DELAY UPON POWER-UP, WAKE-UP AND CLOCK SWITCHING

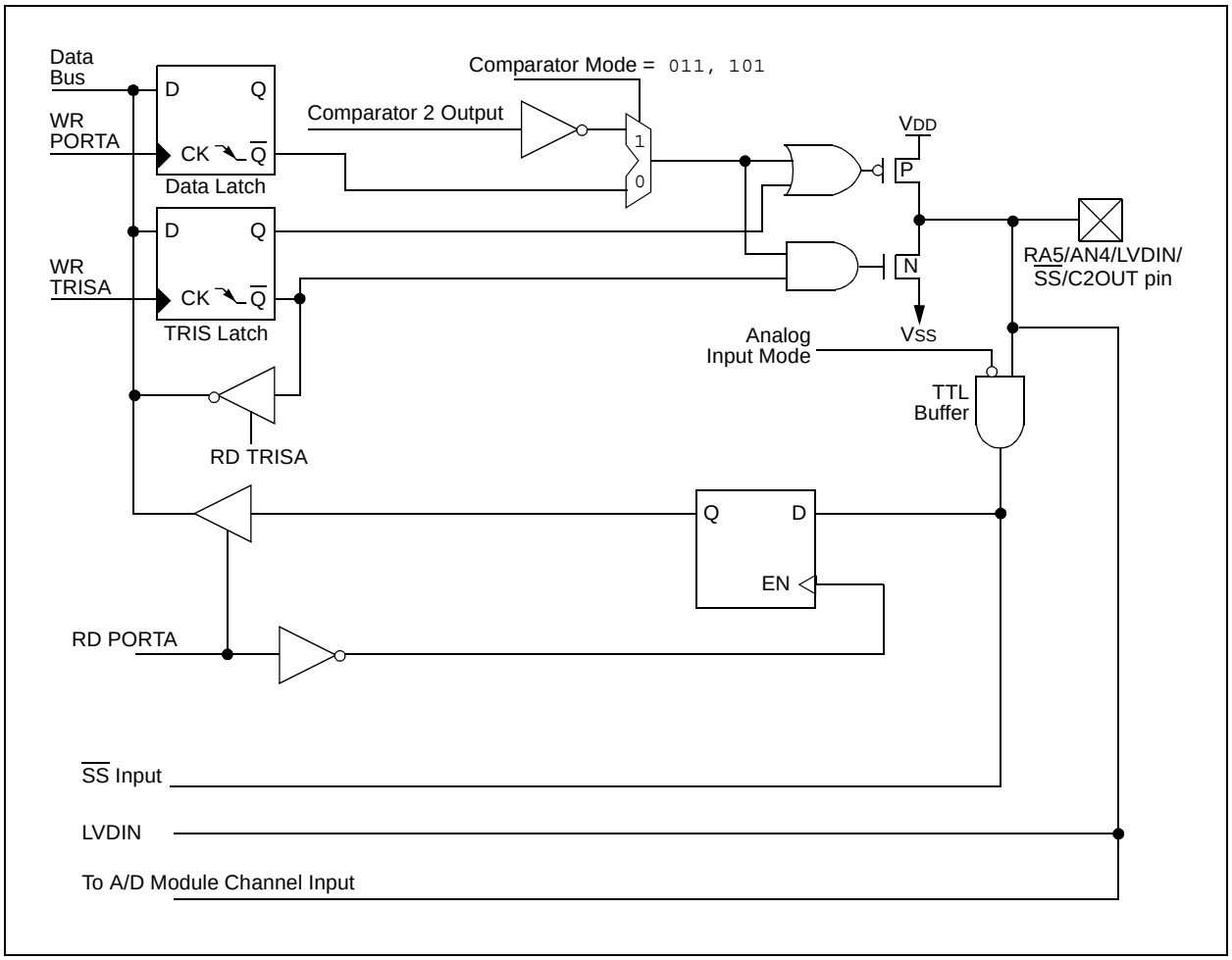
Table 4-3 shows the different delays invoked for various clock switching sequences. It also shows the delays invoked for POR and wake-up.

TABLE 4-3: OSCILLATOR DELAY EXAMPLES

Clock Switch		Frequency	Oscillator Delay	Comments
From	To			
Sleep/POR	INTRC T1OSC	31.25 kHz 32.768 kHz	CPU Start-up(1)	Following a wake-up from Sleep mode or POR, CPU start-up is invoked to allow the CPU to become ready for code execution.
	INTOSC/INTOSC Postscaler	125 kHz-8 MHz	4 ms (approx.) and CPU Start-up(1)	
INTRC/ Sleep	EC, RC	DC – 20 MHz		
INTRC (31.25 kHz)	EC, RC	DC – 20 MHz		
Sleep	LP, XT, HS	32.768 kHz-20 MHz	1024 Clock Cycles	Following a change from INTRC, the OST count of 1024 cycles must occur.
INTRC (31.25 kHz)	INTOSC/INTOSC Postscaler	125 kHz-8 MHz	4 ms (approx.)	Refer to **Section 4.6.4 "Modifying the IRCF Bits"** for further details.

Note 1: The 5 μs-10 μs start-up delay is based on a 1 MHz system clock.

FIGURE 5-5: BLOCK DIAGRAM OF RA5/AN4/LVDIN/$\overline{SS}$/C2OUT PIN

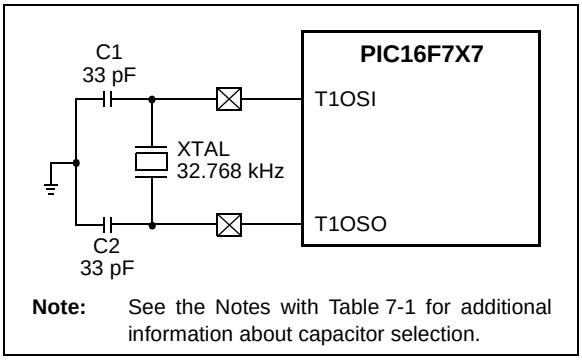


7.6 Timer1 Oscillator

A crystal oscillator circuit is built between pins T1OSI (input) and T1OSO (amplifier output). It is enabled by setting control bit, T1OSCEN (T1CON<3>). The oscillator is a low-power oscillator, rated up to 32.768 kHz. It will continue to run during all power-managed modes. It is primarily intended for a 32 kHz crystal. The circuit for a typical LP oscillator is shown in Figure 7-3. Table 7-1 shows the capacitor selection for the Timer1 oscillator.

The user must provide a software time delay to ensure proper oscillator start-up.

FIGURE 7-3: EXTERNAL COMPONENTS FOR THE TIMER1 LP OSCILLATOR



Note: See the Notes with Table 7-1 for additional information about capacitor selection.

TABLE 7-1: CAPACITOR SELECTION FOR THE TIMER1 OSCILLATOR

Osc Type	Freq	C1	C2
LP	32 kHz	33 pF	33 pF

Note 1: Microchip suggests this value as a starting point in validating the oscillator circuit.

2: Higher capacitance increases the stability of the oscillator but also increases the start-up time.

3: Since each resonator/crystal has its own characteristics, the user should consult the resonator/crystal manufacturer for appropriate values of external components.

4: Capacitor values are for design guidance only.

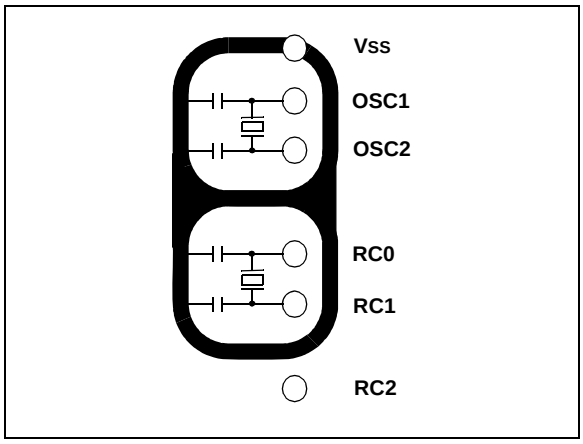
7.7 Timer1 Oscillator Layout Considerations

The Timer1 oscillator circuit draws very little power during operation. Due to the low-power nature of the oscillator, it may also be sensitive to rapidly changing signals in close proximity.

The oscillator circuit, shown in Figure 7-3, should be located as close as possible to the microcontroller. There should be no circuits passing within the oscillator circuit boundaries other than VSS or VDD.

If a high-speed circuit must be located near the oscillator, a grounded guard ring around the oscillator circuit, as shown in Figure 7-4, may be helpful when used on a single sided PCB or in addition to a ground plane.

FIGURE 7-4: OSCILLATOR CIRCUIT WITH GROUNDED GUARD RING



7.8 Resetting Timer1 Using a CCP Trigger Output

If the CCP1 module is configured in Compare mode to generate a “special event trigger” signal (CCP1M3:CCP1M0 = 1011), the signal will reset Timer1 and start an A/D conversion (if the A/D module is enabled).

Note: The special event triggers from the CCP1 module will not set interrupt flag bit, TMR1IF (PIR1<0>).

Timer1 must be configured for either Timer or Synchronized Counter mode to take advantage of this feature. If Timer1 is running in Asynchronous Counter mode, this Reset operation may not work.

In the event that a write to Timer1 coincides with a special event trigger from CCP1, the write will take precedence.

In this mode of operation, the CCPR1H:CCPR1L register pair effectively becomes the period register for Timer1.

FIGURE 10-11: I²C™ SLAVE MODE TIMING (TRANSMISSION, 10-BIT ADDRESS)

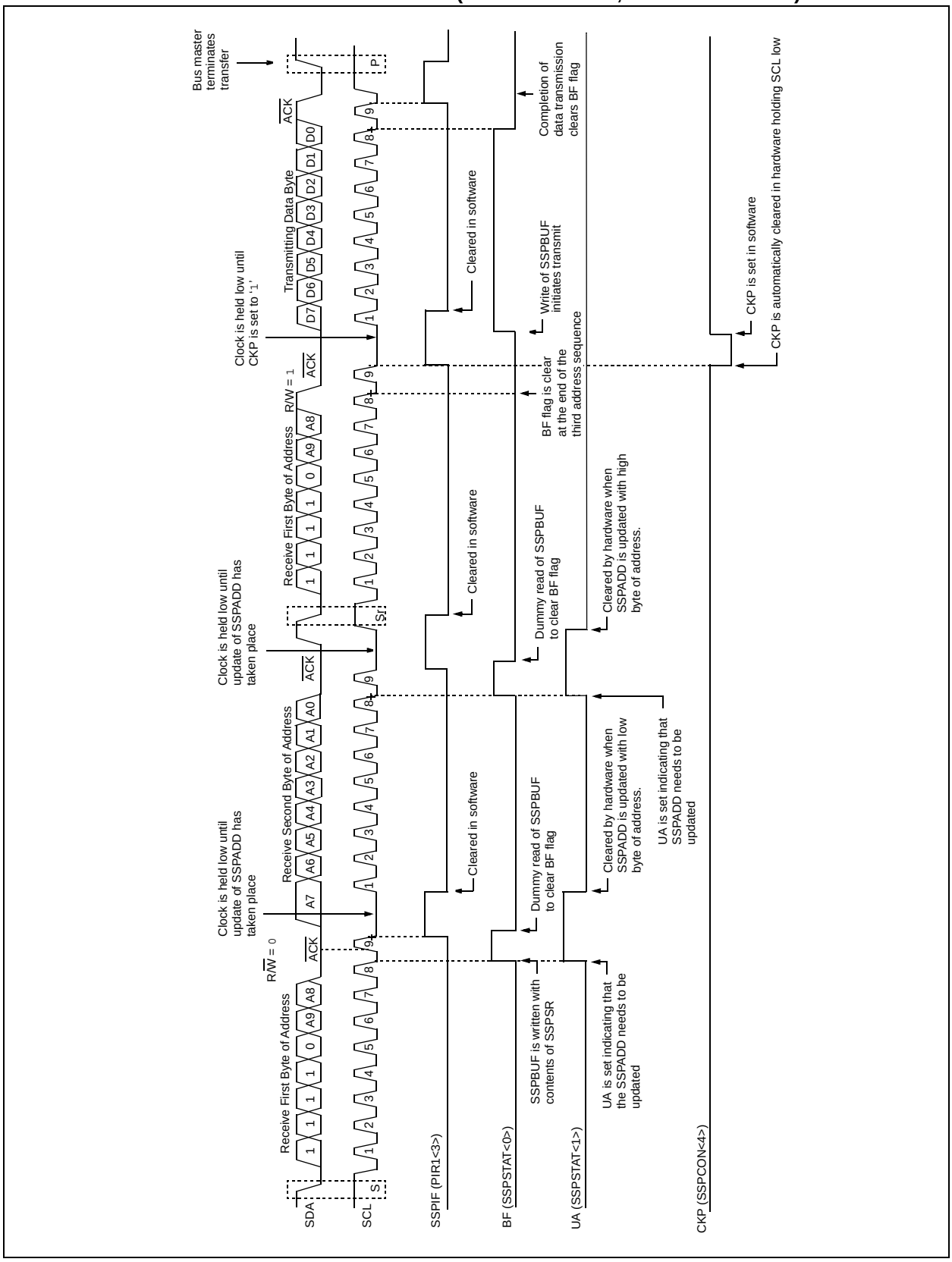


TABLE 11-3: BAUD RATES FOR ASYNCHRONOUS MODE (BRGH = 0)

Baud Rate (K)	Fosc = 20 MHz			Fosc = 16 MHz			Fosc = 10 MHz		
	Kbaud	% Error	SPBRG Value (decimal)	Kbaud	% Error	SPBRG Value (decimal)	Kbaud	% Error	SPBRG Value (decimal)
0.3	—	—	—	—	—	—	—	—	—
1.2	1.221	1.75	255	1.202	0.17	207	1.202	0.17	129
2.4	2.404	0.17	129	2.404	0.17	103	2.404	0.17	64
9.6	9.766	1.73	31	9.615	0.16	25	9.766	1.73	15
19.2	19.531	1.72	15	19.231	0.16	12	19.531	1.72	7
28.8	31.250	8.51	9	27.778	3.55	8	31.250	8.51	4
33.6	34.722	3.34	8	35.714	6.29	6	31.250	6.99	4
57.6	62.500	8.51	4	62.500	8.51	3	52.083	9.58	2
HIGH	1.221	—	255	0.977	—	255	0.610	—	255
LOW	312.500	—	0	250.000	—	0	156.250	—	0

Baud Rate (K)	Fosc = 4 MHz			Fosc = 3.6864 MHz		
	Kbaud	% Error	SPBRG Value (decimal)	Kbaud	% Error	SPBRG Value (decimal)
0.3	0.300	0	207	0.3	0	191
1.2	1.202	0.17	51	1.2	0	47
2.4	2.404	0.17	25	2.4	0	23
9.6	8.929	6.99	6	9.6	0	5
19.2	20.833	8.51	2	19.2	0	2
28.8	31.250	8.51	1	28.8	0	1
33.6	—	—	—	—	—	—
57.6	62.500	8.51	0	57.6	0	0
HIGH	0.244	—	255	0.225	—	255
LOW	62.500	—	0	57.6	—	0

TABLE 11-4: BAUD RATES FOR ASYNCHRONOUS MODE (BRGH = 1)

Baud Rate (K)	Fosc = 20 MHz			Fosc = 16 MHz			Fosc = 10 MHz		
	Kbaud	% Error	SPBRG Value (decimal)	Kbaud	% Error	SPBRG Value (decimal)	Kbaud	% Error	SPBRG Value (decimal)
0.3	—	—	—	—	—	—	—	—	—
1.2	—	—	—	—	—	—	—	—	—
2.4	—	—	—	—	—	—	2.441	1.71	255
9.6	9.615	0.16	129	9.615	0.16	103	9.615	0.16	64
19.2	19.231	0.16	64	19.231	0.16	51	19.531	1.72	31
28.8	29.070	0.94	42	29.412	2.13	33	28.409	1.36	21
33.6	33.784	0.55	36	33.333	0.79	29	32.895	2.10	18
57.6	59.524	3.34	20	58.824	2.13	16	56.818	1.36	10
HIGH	4.883	—	255	3.906	—	255	2.441	—	255
LOW	1250.000	—	0	1000.000	—	0	625.000	—	0

Baud Rate (K)	Fosc = 4 MHz			Fosc = 3.6864 MHz		
	Kbaud	% Error	SPBRG Value (decimal)	Kbaud	% Error	SPBRG Value (decimal)
0.3	—	—	—	—	—	—
1.2	1.202	0.17	207	1.2	0	191
2.4	2.404	0.17	103	2.4	0	95
9.6	9.615	0.16	25	9.6	0	23
19.2	19.231	0.16	12	19.2	0	11
28.8	27.798	3.55	8	28.8	0	7
33.6	35.714	6.29	6	32.9	2.04	6
57.6	62.500	8.51	3	57.6	0	3
HIGH	0.977	—	255	0.9	—	255
LOW	250.000	—	0	230.4	—	0

11.3.2 AUSART SYNCHRONOUS MASTER RECEPTION

Once Synchronous mode is selected, reception is enabled by setting either enable bit, SREN (RCSTA<5>) or enable bit, CREN (RCSTA<4>). Data is sampled on the RC7/RX/DT pin on the falling edge of the clock. If enable bit SREN is set, then only a single word is received. If enable bit CREN is set, the reception is continuous until CREN is cleared. If both bits are set, CREN takes precedence. After clocking the last bit, the received data in the Receive Shift Register (RSR) is transferred to the RCREG register (if it is empty). When the transfer is complete, interrupt flag bit, RCIF (PIR1<5>), is set. The actual interrupt can be enabled/disabled by setting/clearing enable bit, RCIE (PIE1<5>). Flag bit RCIF is a read-only bit which is reset by the hardware. In this case, it is reset when the RCREG register has been read and is empty. The RCREG is a double-buffered register (i.e., it is a two-deep FIFO). It is possible for two bytes of data to be received and transferred to the RCREG FIFO and a third byte to begin shifting into the RSR register. On the clocking of the last bit of the third byte, if the RCREG register is still full, then Overrun Error bit, OERR (RCSTA<1>), is set. The word in the RSR will be lost. The RCREG register can be read twice to retrieve the two bytes in the FIFO. Bit OERR has to be cleared in software (by clearing bit CREN). If bit OERR is set, transfers from the RSR to the RCREG are inhibited, so it is essential to clear bit OERR if it is set. The ninth receive bit is buffered the same way as the receive data. Reading the RCREG register will load bit RX9D with a new value; therefore, it is essential for the user to read the RCSTA register before reading RCREG in order not to lose the old RX9D information.

When setting up a Synchronous Master Reception:

1. Initialize the SPBRG register for the appropriate baud rate (see **Section 11.1 “AUSART Baud Rate Generator (BRG)”**).
2. Enable the synchronous master serial port by setting bits SYNC, SPEN and CSRC.
3. Ensure bits CREN and SREN are clear.
4. If interrupts are desired, then set enable bit RCIE.
5. If 9-bit reception is desired, then set bit RX9.
6. If a single reception is required, set bit SREN. For continuous reception, set bit CREN.
7. Interrupt flag bit RCIF will be set when reception is complete and an interrupt will be generated if enable bit RCIE was set.
8. Read the RCSTA register to get the ninth bit (if enabled) and determine if any error occurred during reception.
9. Read the 8-bit received data by reading the RCREG register.
10. If any error occurred, clear the error by clearing bit CREN.
11. If using interrupts, ensure that GIE and PEIE (bits 7 and 6) of the INTCON register are set.

TABLE 11-11: REGISTERS ASSOCIATED WITH SYNCHRONOUS MASTER RECEPTION

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other Resets
0Bh, 8Bh, 10Bh,18Bh	INTCON	GIE	PEIE	TMR0IE	INT0IE	RBIE	TMR0IF	INT0IF	RBIF	0000 000x	0000 000u
0Ch	PIR1	PSPIF(1)	ADIF	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	0000 0000	0000 0000
18h	RCSTA	SPEN	RX9	SREN	CREN	ADDEN	FERR	OERR	RX9D	0000 000x	0000 000x
1Ah	RCREG	AUSART Receive Register								0000 0000	0000 0000
8Ch	PIE1	PSPIE(1)	ADIE	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	0000 0000	0000 0000
98h	TXSTA	CSRC	TX9	TXEN	SYNC	—	BRGH	TRMT	TX9D	0000 -010	0000 -010
99h	SPBRG	Baud Rate Generator Register								0000 0000	0000 0000

Legend: x = unknown, — = unimplemented, read as ‘0’. Shaded cells are not used for synchronous master reception.

Note 1: Bits PSPIE and PSPIF are reserved on 28-pin devices; always maintain these bits clear.

REGISTER 12-2: ADCON1: A/D CONTROL REGISTER 1 (ADDRESS 9Fh)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
ADFM	ADCS2	VCFG1	VCFG0	PCFG3	PCFG2	PCFG1	PCFG0
bit 7							bit 0

bit 7 **ADFM:** A/D Result Format Select bit
1 = Right justified. Six Most Significant bits of ADRESH are read as '0'.
0 = Left justified. Six Least Significant bits of ADRESL are read as '0'.

bit 6 **ADCS2:** A/D Clock Divide by 2 Select bit
1 = A/D clock source is divided by two when system clock is used
0 = Disabled

bit 5 **VCFG1:** Voltage Reference Configuration bit 1
0 = V_{REF-} is connected to V_{SS}
1 = V_{REF-} is connected to external V_{REF-} (RA2)

bit 4 **VCFG0:** Voltage Reference Configuration bit 0
0 = V_{REF+} is connected to V_{DD}
1 = V_{REF+} is connected to external V_{REF+} (RA3)

bit 3-0 **PCFG<3:0>:** A/D Port Configuration bits

	AN13	AN12	AN11	AN10	AN9	AN8	AN7	AN6	AN5	AN4	AN3	AN2	AN1	AN0
0000	A	A	A	A	A	A	A	A	A	A	A	A	A	A
0001	A	A	A	A	A	A	A	A	A	A	A	A	A	A
0010	D	A	A	A	A	A	A	A	A	A	A	A	A	A
0011	D	D	A	A	A	A	A	A	A	A	A	A	A	A
0100	D	D	D	A	A	A	A	A	A	A	A	A	A	A
0101	D	D	D	D	A	A	A	A	A	A	A	A	A	A
0110	D	D	D	D	D	A	A	A	A	A	A	A	A	A
0111	D	D	D	D	D	D	A	A	A	A	A	A	A	A
1000	D	D	D	D	D	D	D	A	A	A	A	A	A	A
1001	D	D	D	D	D	D	D	D	A	A	A	A	A	A
1010	D	D	D	D	D	D	D	D	D	A	A	A	A	A
1011	D	D	D	D	D	D	D	D	D	D	A	A	A	A
1100	D	D	D	D	D	D	D	D	D	D	D	A	A	A
1101	D	D	D	D	D	D	D	D	D	D	D	D	A	A
1110	D	D	D	D	D	D	D	D	D	D	D	D	D	A
1111	D	D	D	D	D	D	D	D	D	D	D	D	D	D

Legend: A = Analog input, D = Digital I/O

Note: AN5 through AN7 are only available on the 40-pin product variant (PIC16F747 and PIC16F777).

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

12.1 A/D Acquisition Requirements

For the A/D converter to meet its specified accuracy, the charge holding capacitor (CHOLD) must be allowed to fully charge to the input channel voltage level. The analog input model is shown in Figure 12-2. The source impedance (RS) and the internal sampling switch (RSS) impedance directly affect the time required to charge the capacitor CHOLD. The sampling switch (RSS) impedance varies over the device voltage (VDD), see Figure 12-2. **The maximum recommended impedance for analog sources is 2.5 kΩ.** As the impedance is decreased, the acquisition time may be decreased. After the analog input channel is selected (changed), this acquisition must be done before the conversion can be started.

To calculate the minimum acquisition time, Equation 12-1 may be used. This equation assumes that 1/2 LSb error is used (1024 steps for the A/D). The 1/2 LSb error is the maximum error allowed for the A/D to meet its specified resolution.

To calculate the minimum acquisition time, TACQ, see the *"PIC® Mid-Range MCU Family Reference Manual"* (DS33023).

EQUATION 12-1: ACQUISITION TIME

TACQ = Amplifier Settling Time + Hold Capacitor Charging Time + Temperature Coefficient

= TAMP + TC + TCOFF
= 2 µs + TC + [(Temperature – 25°C)(0.05 µs/°C)]
TC = CHOLD (RIC + RSS + RS) In(1/2047)
= -120 pF (1 kΩ + 7 kΩ + 10 kΩ) In(0.0004885)
= 16.47 µs
TACQ = 2 µs + 16.47 µs + [(50°C – 25°C)(0.05 µs/°C)
= 19.72 µs

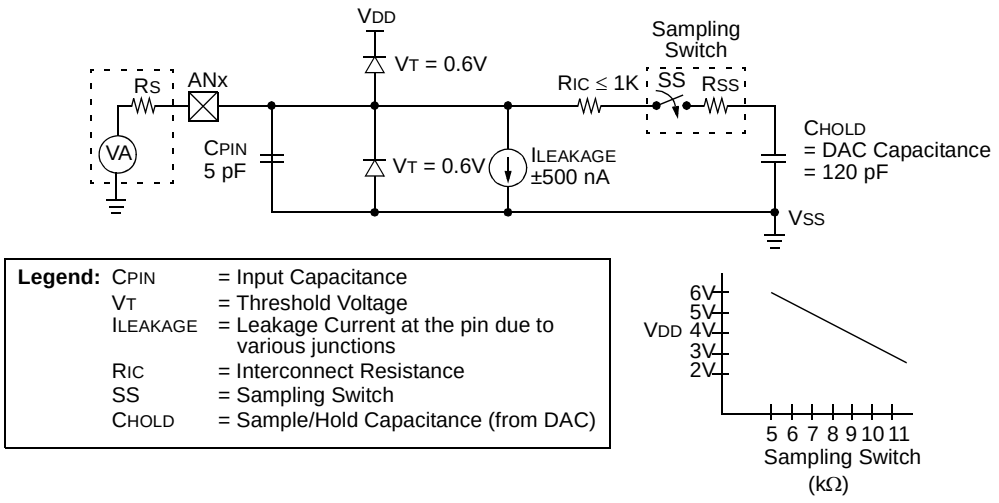
Note 1: The reference voltage (VREF) has no effect on the equation since it cancels itself out.

2: The charge holding capacitor (CHOLD) is not discharged after each conversion.

3: The maximum recommended impedance for analog sources is 10 kΩ. This is required to meet the pin leakage specification.

4: After a conversion has completed, a 2.0 TAD delay must complete before acquisition can begin again. During this time, the holding capacitor is not connected to the selected A/D input channel.

FIGURE 12-2: ANALOG INPUT MODEL

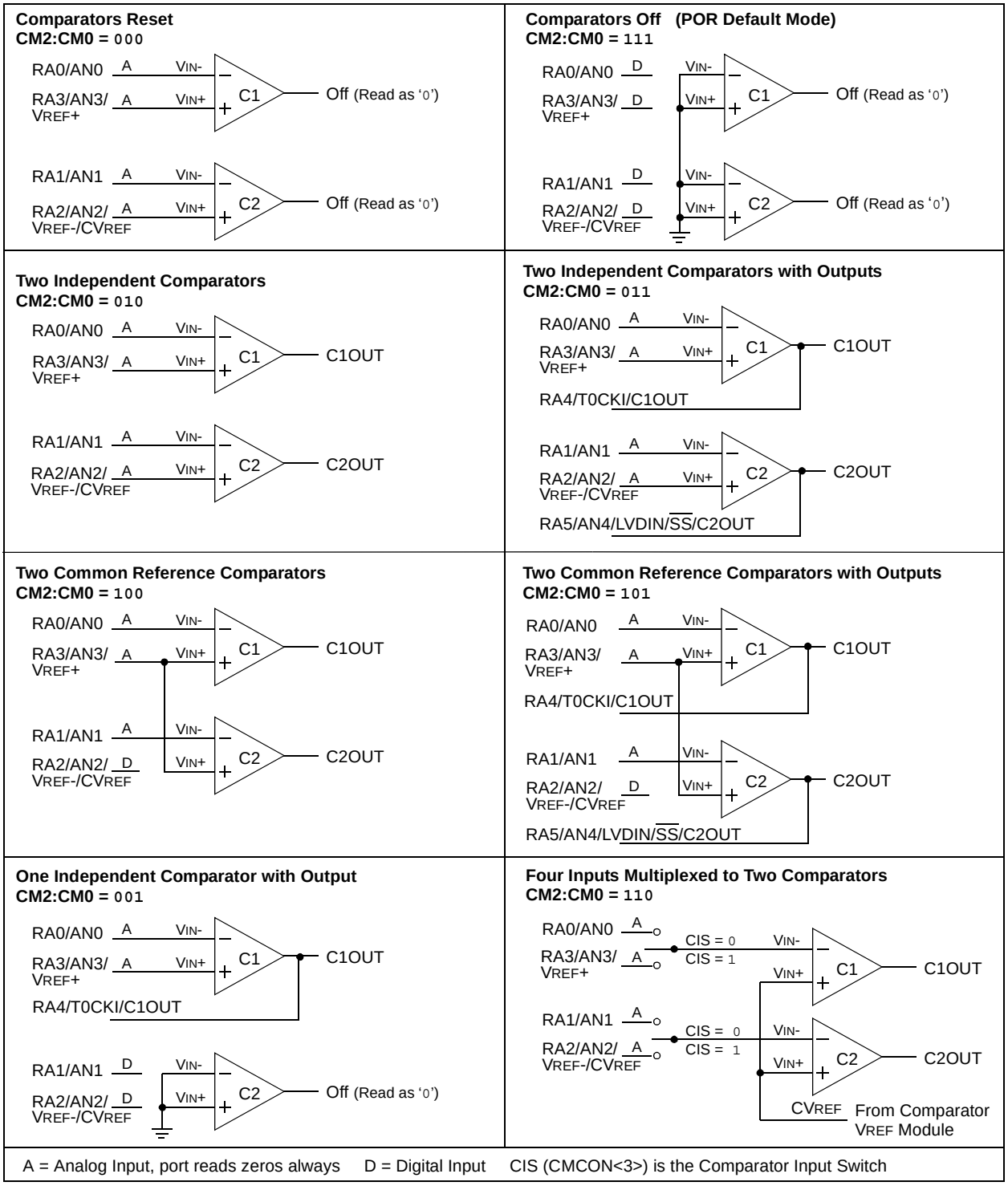


13.1 Comparator Configuration

There are eight modes of operation for the comparators. The CMCON register is used to select these modes. Figure 13-1 shows the eight possible modes. The TRISA register controls the data direction of the comparator pins for each mode. If the Comparator mode is changed, the comparator output level may not be valid for the specified mode change delay shown in the electrical specifications (**Section 18.0 "Electrical Characteristics"**).

Note:	Comparator interrupts should be disabled during a Comparator mode change. Otherwise, a false interrupt may occur.

FIGURE 13-1: COMPARATOR I/O OPERATING MODES



A = Analog Input, port reads zeros always D = Digital Input CIS (CMCON<3>) is the Comparator Input Switch

15.15 Interrupts

The PIC16F7X7 has up to 17 sources of interrupt. The Interrupt Control register (INTCON) records individual interrupt requests in flag bits. It also has individual and global interrupt enable bits.

Note:	Individual interrupt flag bits are set regardless of the status of their corresponding mask bit or the GIE bit.

A Global Interrupt Enable bit, GIE (INTCON<7>), enables (if set) all unmasked interrupts or disables (if cleared) all interrupts. When bit GIE is enabled and an interrupt's flag bit and mask bit are set, the interrupt will vector immediately. Individual interrupts can be disabled through their corresponding enable bits in various registers. Individual interrupt bits are set regardless of the status of the GIE bit. The GIE bit is cleared on Reset.

The "return from interrupt" instruction, `RETFIE`, exits the interrupt routine as well as sets the GIE bit which re-enables interrupts.

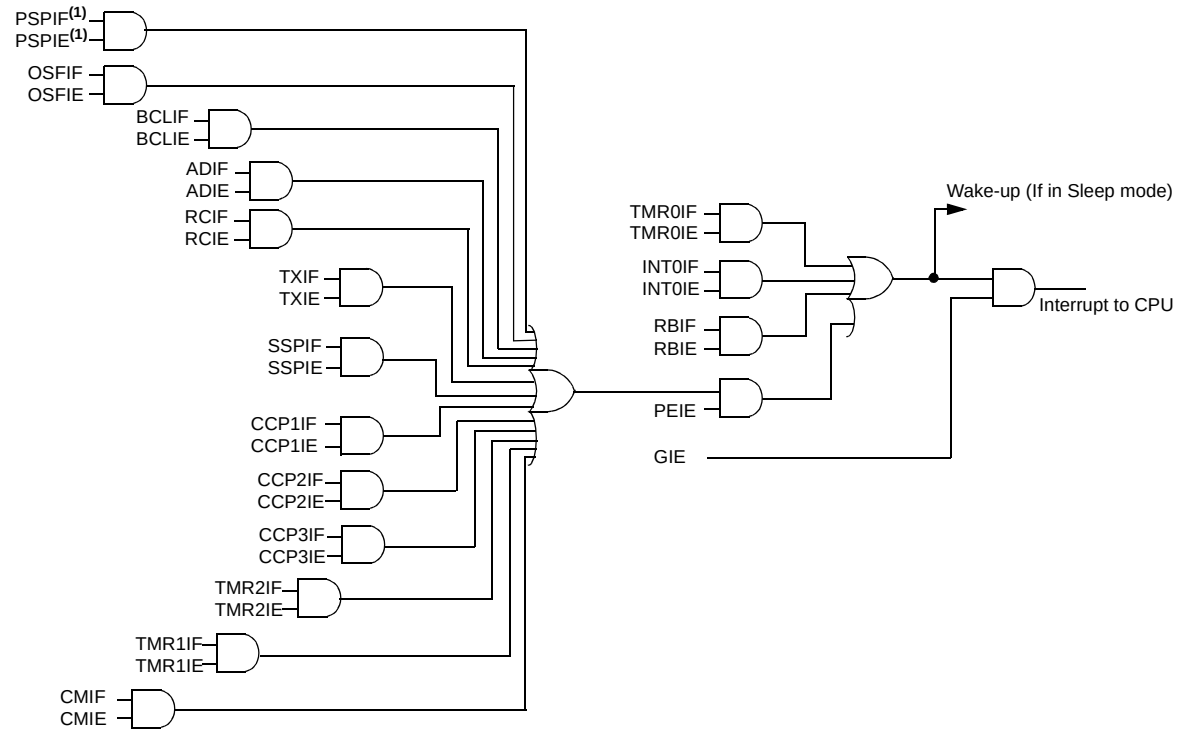
The RB0/INT pin interrupt, the RB port change interrupt and the TMR0 overflow interrupt flags are contained in the INTCON register.

The peripheral interrupt flags are contained in the Special Function Register, PIR1. The corresponding interrupt enable bits are contained in Special Function Register, PIE1 and the peripheral interrupt enable bit is contained in Special Function Register, INTCON.

When an interrupt is serviced, the GIE bit is cleared to disable any further interrupt, the return address is pushed onto the stack and the PC is loaded with 0004h. Once in the Interrupt Service Routine, the source(s) of the interrupt can be determined by polling the interrupt flag bits. The interrupt flag bit(s) must be cleared in software before re-enabling interrupts to avoid recursive interrupts.

For external interrupt events, such as the INT pin or PORTB change interrupt, the interrupt latency will be three or four instruction cycles. The exact latency depends on when the interrupt event occurs relative to the current Q cycle. The latency is the same for one or two-cycle instructions. Individual interrupt flag bits are set regardless of the status of their corresponding mask bit, PEIE bit or the GIE bit.

FIGURE 15-11: INTERRUPT LOGIC



Note 1: PSP interrupt is implemented only on PIC16F747/777 devices.

15.18.2 WAKE-UP USING INTERRUPTS

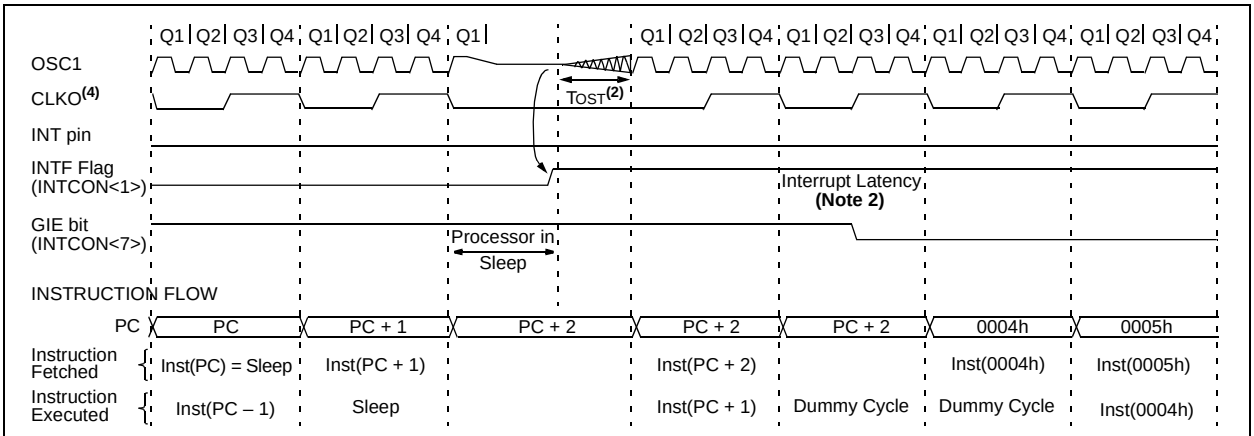
When global interrupts are disabled (GIE cleared) and any interrupt source has both its interrupt enable bit and interrupt flag bit set, one of the following will occur:

- If the interrupt occurs **before** the execution of a SLEEP instruction, the SLEEP instruction will complete as a NOP. Therefore, the WDT and WDT prescaler and postscaler (if enabled) will not be cleared, the $\overline{TO}$ bit will not be set and the $\overline{PD}$ bit will not be cleared.
- If the interrupt occurs **during or after** the execution of a SLEEP instruction, the device will immediately wake-up from Sleep. The SLEEP instruction will be completely executed before the wake-up. Therefore, the WDT and WDT prescaler and postscaler (if enabled) will be cleared, the $\overline{TO}$ bit will be set and the $\overline{PD}$ bit will be cleared.

Even if the flag bits were checked before executing a SLEEP instruction, it may be possible for flag bits to become set before the SLEEP instruction completes. To determine whether a SLEEP instruction executed, test the $\overline{PD}$ bit. If the $\overline{PD}$ bit is set, the SLEEP instruction was executed as a NOP.

To ensure that the WDT is cleared, a CLRWDT instruction should be executed before a SLEEP instruction.

FIGURE 15-16: WAKE-UP FROM SLEEP THROUGH INTERRUPT



Note 1: XT, HS or LP Oscillator mode assumed.
2: TOST = 1024 TOSC (drawing not to scale). This delay will not be there for RC Oscillator mode.
3: GIE = 1 assumed. In this case, after wake-up, the processor jumps to the interrupt routine. If GIE = 0, execution will continue in-line.
4: CLKO is not available in these oscillator modes but shown here for timing reference.

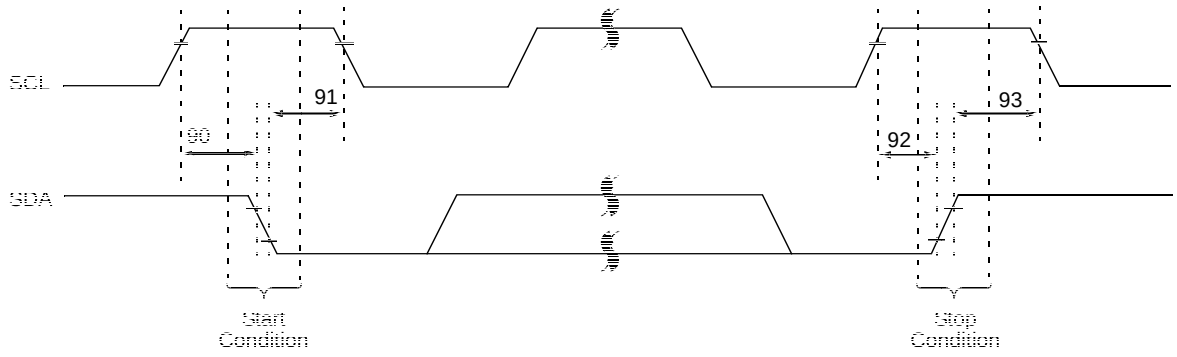
TABLE 18-10: SPI MODE REQUIREMENTS

Param No.	Symbol	Characteristic		Min	Typ†	Max	Units	Conditions
70*	TssL2scH, TssL2scL	$\overline{SS}$ ↓ to SCK ↓ or SCK ↑ Input		Tcy	—	—	ns	
71*	TscH	SCK Input High Time (Slave mode)		Tcy + 20	—	—	ns	
72*	TscL	SCK Input Low Time (Slave mode)		Tcy + 20	—	—	ns	
73*	TdiV2scH, TdiV2scL	Setup Time of SDI Data Input to SCK Edge		100	—	—	ns	
74*	TscH2diL, TscL2diL	Hold Time of SDI Data Input to SCK Edge		100	—	—	ns	
75*	TdoR	SDO Data Output Rise Time	PIC16F7X7 PIC16LF7X7	— —	10 25	25 50	ns ns	
76*	TdoF	SDO Data Output Fall Time		—	10	25	ns	
77*	TssH2doZ	$\overline{SS}$ ↑ to SDO Output High-Impedance		10	—	50	ns	
78*	TscR	SCK Output Rise Time (Master mode)	PIC16F7X7 PIC16LF7X7	— —	10 25	25 50	ns ns	
79*	TscF	SCK Output Fall Time (Master mode)		—	10	25	ns	
80*	TscH2doV, TscL2doV	SDO Data Output Valid after SCK Edge	PIC16F7X7 PIC16LF7X7	— —	— —	50 145	ns ns	
81*	TdoV2scH, TdoV2scL	SDO Data Output Setup to SCK Edge		Tcy	—	—	ns	
82*	TssL2doV	SDO Data Output Valid after $\overline{SS}$ ↓ Edge		—	—	50	ns	
83*	TscH2ssH, TscL2ssH	$\overline{SS}$ ↑ after SCK Edge		1.5 Tcy + 40	—	—	ns	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

FIGURE 18-16: I^2C™ BUS START/STOP BITS TIMING



Note: Refer to Figure 18-4 for load conditions.

FIGURE 19-3: TYPICAL IDD vs. FOSC OVER VDD (XT MODE)

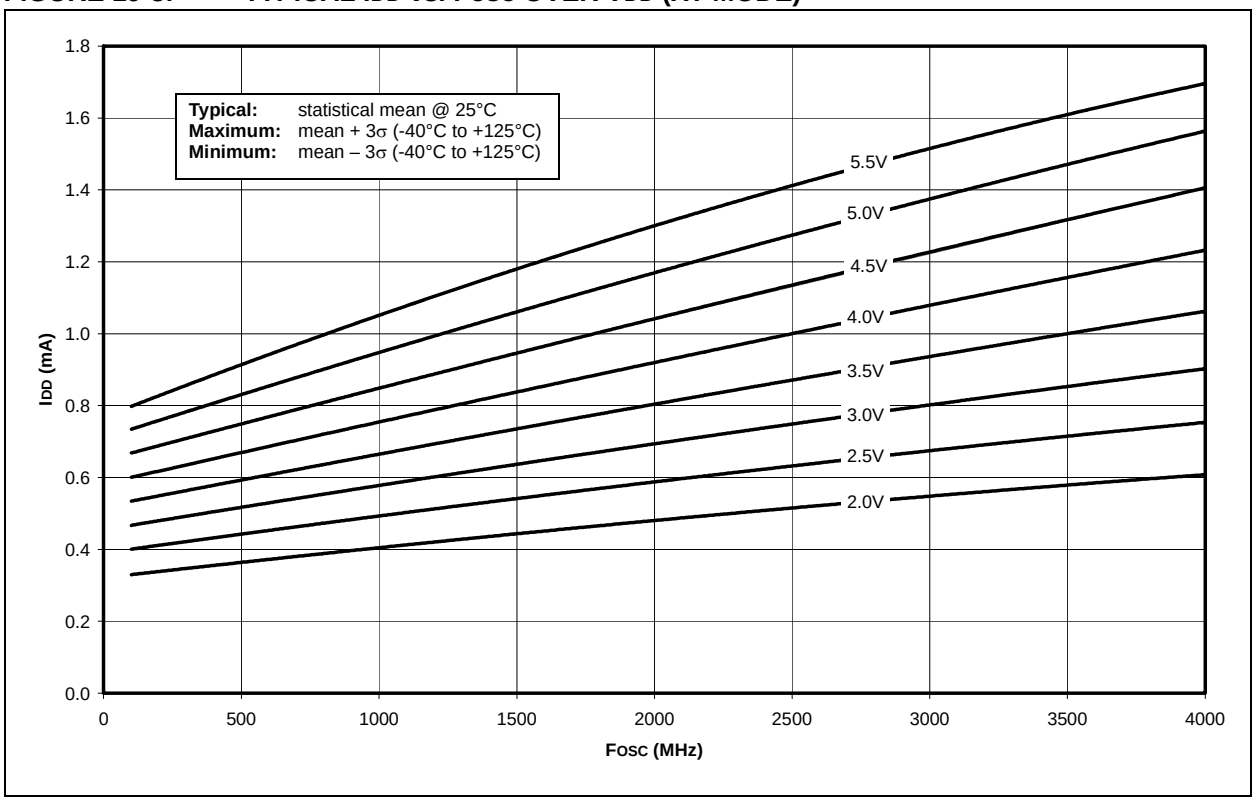


FIGURE 19-4: MAXIMUM IDD vs. FOSC OVER VDD (XT MODE)

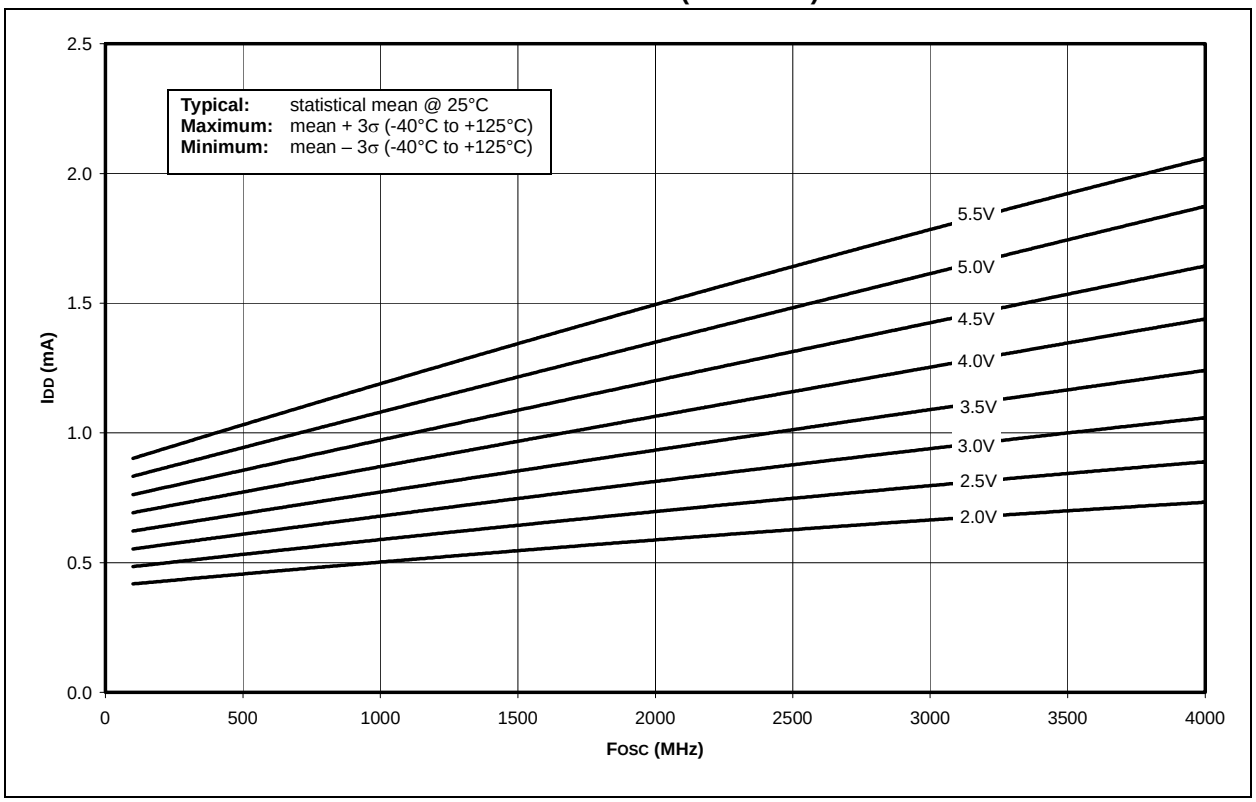


FIGURE 19-13: AVERAGE FOSC VS. VDD FOR VARIOUS VALUES OF R (RC MODE, C = 300 pF, +25°C)

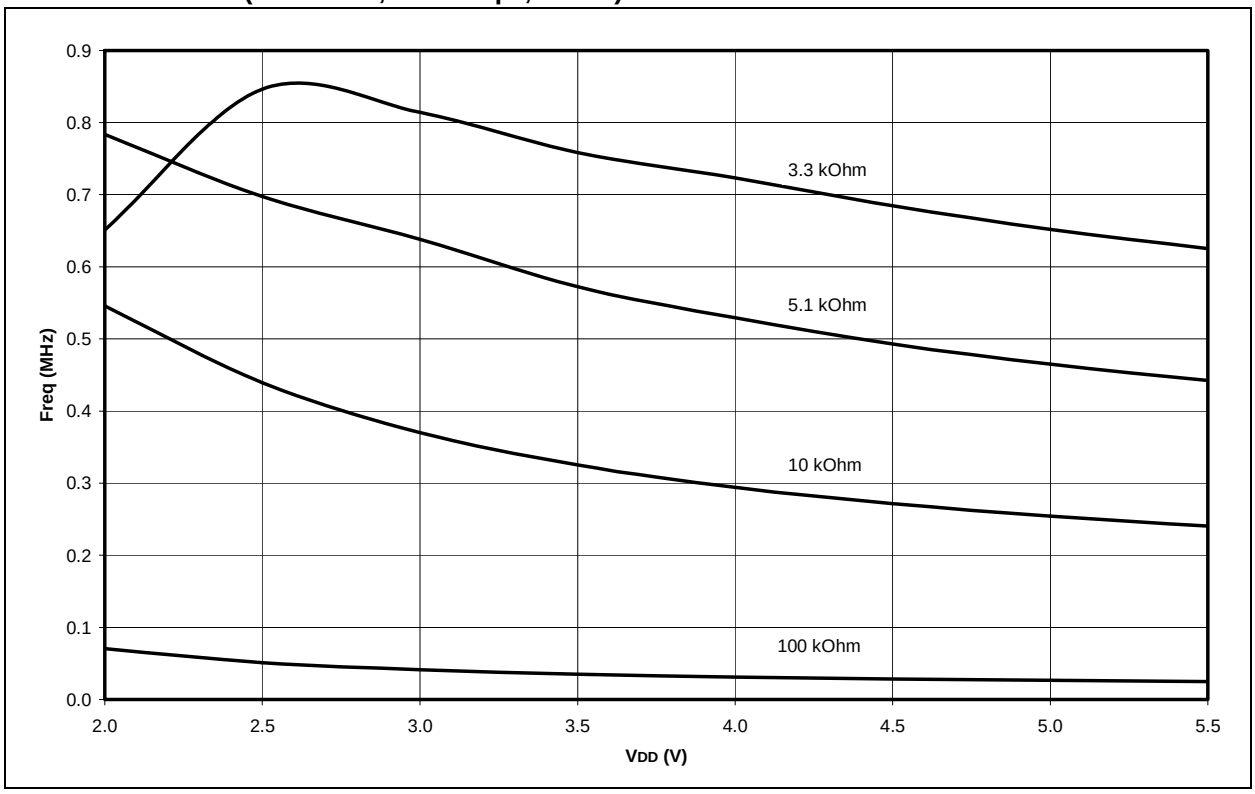
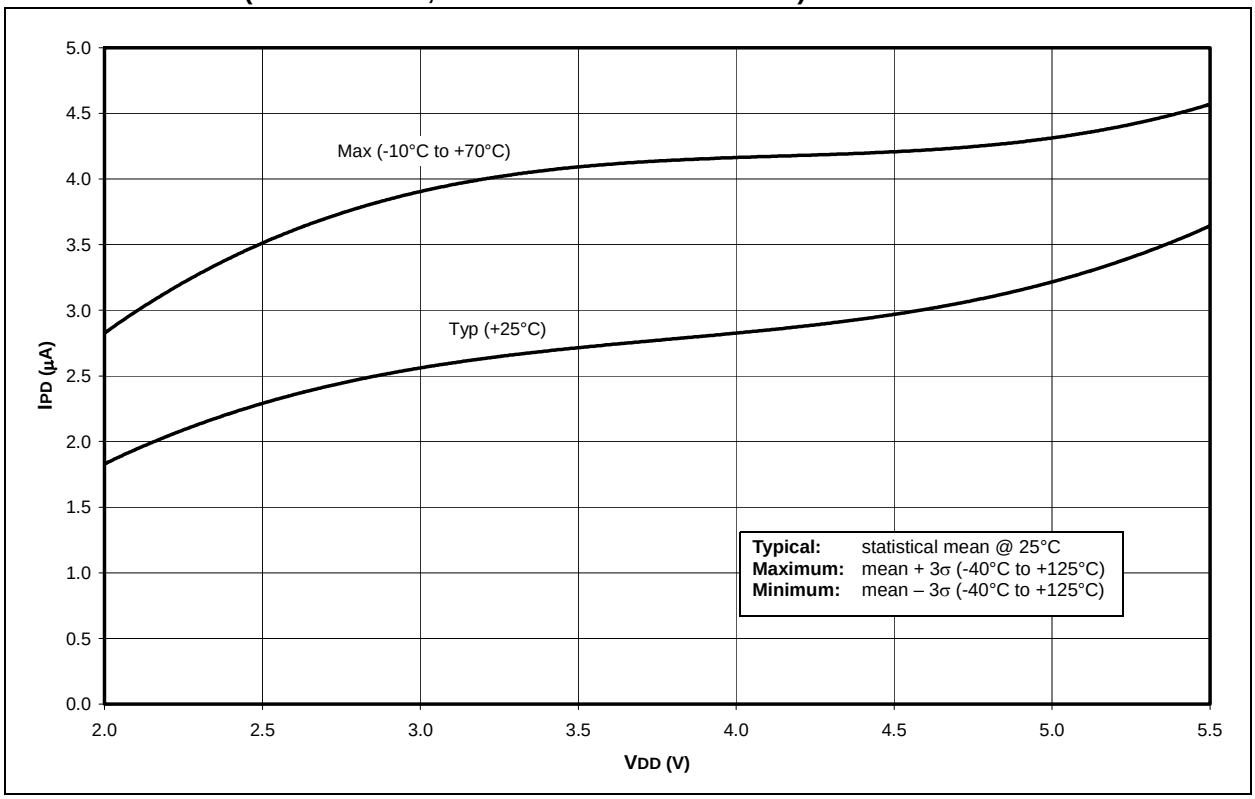


FIGURE 19-14: ΔIPD TIMER1 OSCILLATOR, -10°C TO +70°C (SLEEP MODE, TMR1 COUNTER DISABLED)

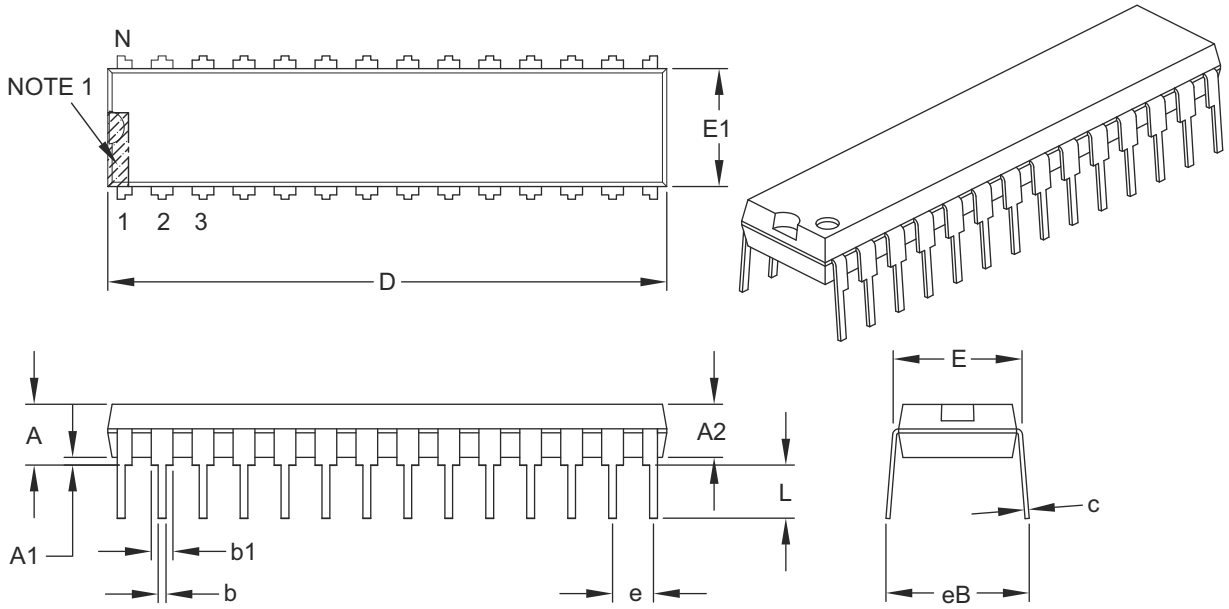


20.2 Package Details

The following sections give the technical details of the packages.

28-Lead Skinny Plastic Dual In-Line (SP) – 300 mil Body [SPDIP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		INCHES		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		28	
Pitch	e		.100 BSC	
Top to Seating Plane	A	–	–	.200
Molded Package Thickness	A2	.120	.135	.150
Base to Seating Plane	A1	.015	–	–
Shoulder to Shoulder Width	E	.290	.310	.335
Molded Package Width	E1	.240	.285	.295
Overall Length	D	1.345	1.365	1.400
Tip to Seating Plane	L	.110	.130	.150
Lead Thickness	c	.008	.010	.015
Upper Lead Width	b1	.040	.050	.070
Lower Lead Width	b	.014	.018	.022
Overall Row Spacing §	eB	–	–	.430

Notes:

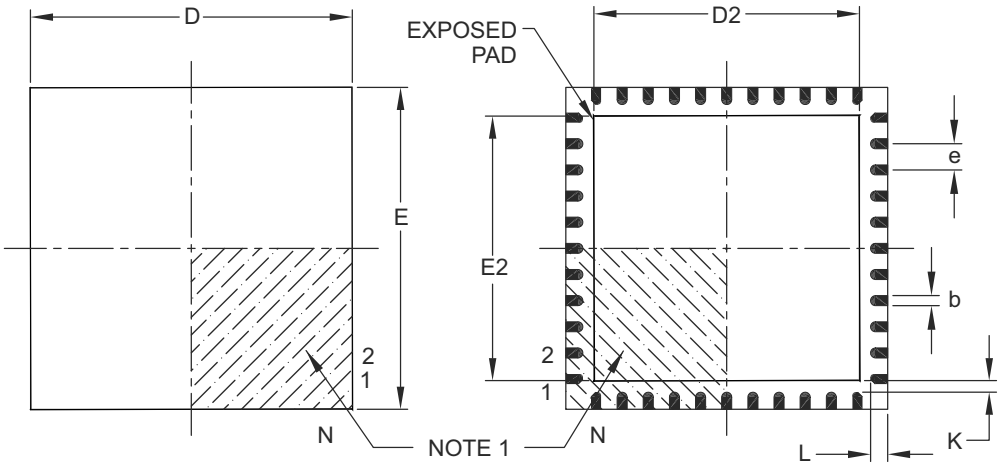
1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic.
3. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

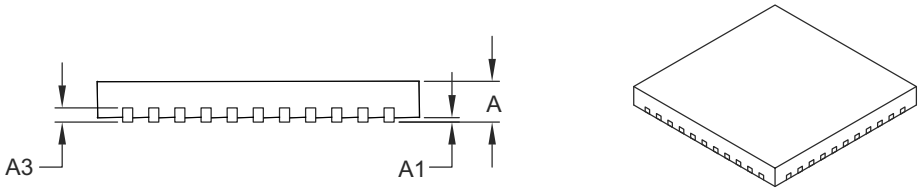
Microchip Technology Drawing C04-070B

44-Lead Plastic Quad Flat, No Lead Package (ML) – 8x8 mm Body [QFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



TOP VIEW **BOTTOM VIEW**



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		44	
Pitch	e		0.65 BSC	
Overall Height	A	0.80	0.90	1.00
Standoff	A1	0.00	0.02	0.05
Contact Thickness	A3		0.20 REF	
Overall Width	E		8.00 BSC	
Exposed Pad Width	E2	6.30	6.45	6.80
Overall Length	D		8.00 BSC	
Exposed Pad Length	D2	6.30	6.45	6.80
Contact Width	b	0.25	0.30	0.38
Contact Length	L	0.30	0.40	0.50
Contact-to-Exposed Pad	K	0.20	–	–

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated.
3. Dimensioning and tolerancing per ASME Y14.5M.

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

   REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-103B

INDEX

A

B